

484-Ball Fine-Pitch BGA (FG484/FGG484) Package

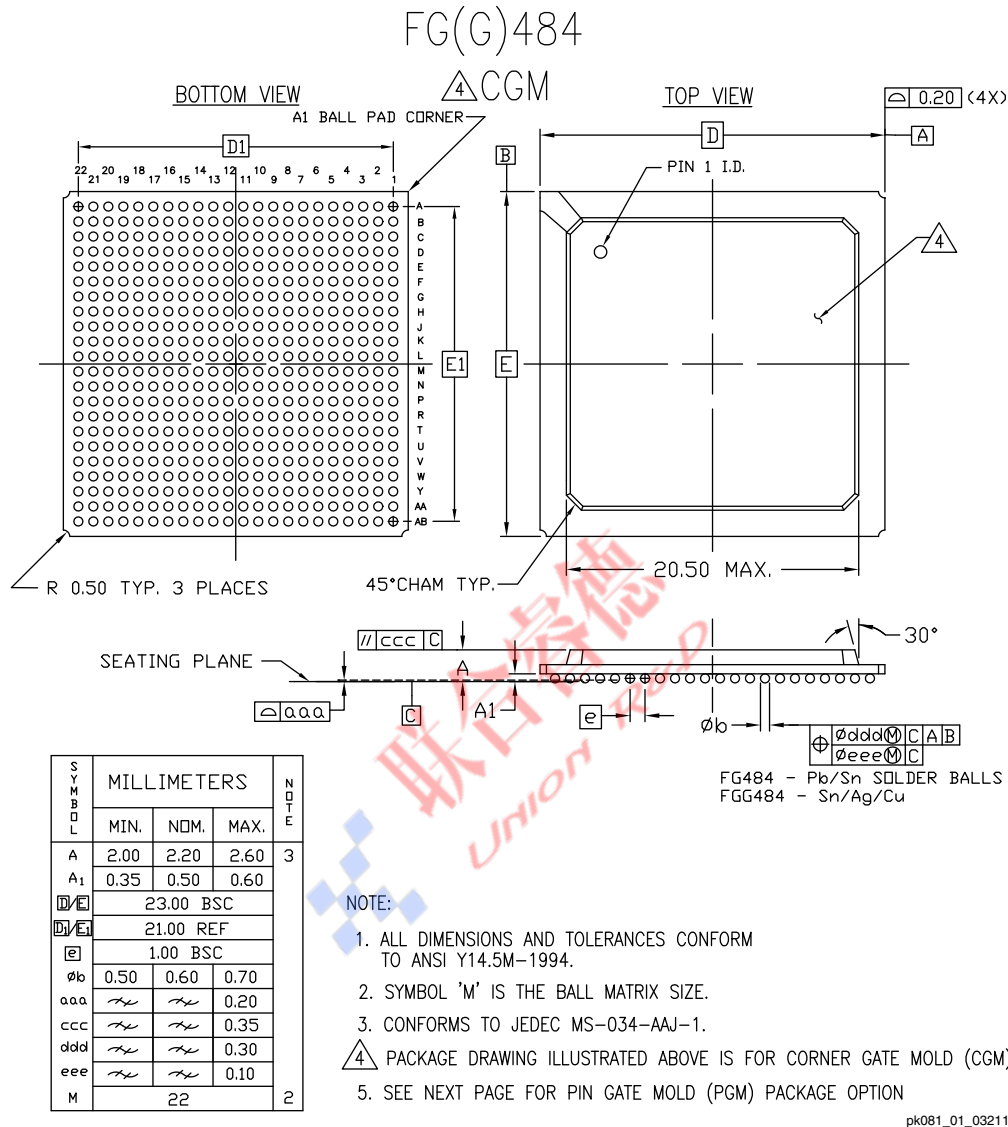


Figure 1: Corner Gate Mold Option, FG484/FGG484 Package

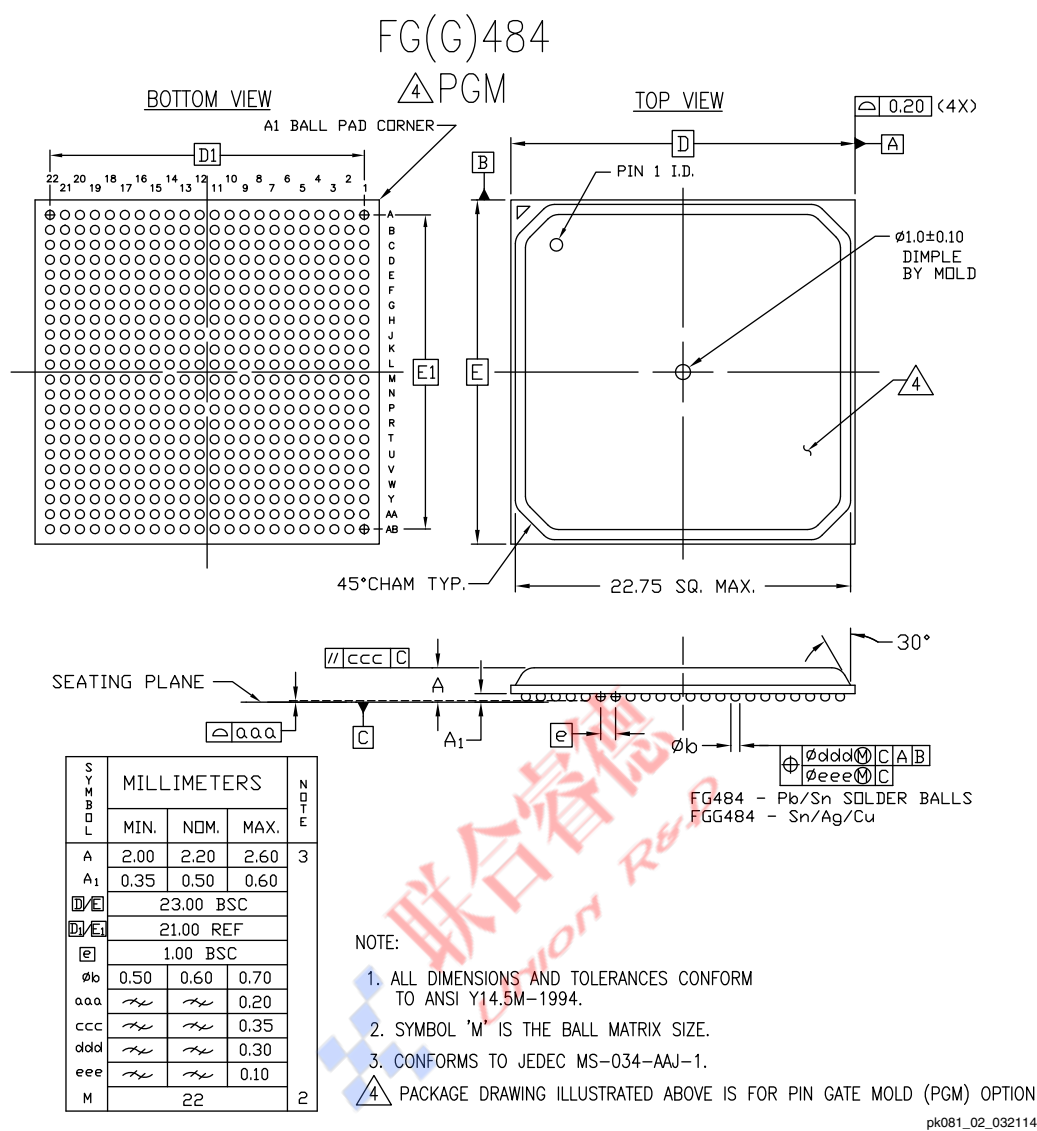


Figure 2: Pin Gate Mold Option, FG484/FGG484 Package

Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
03/01/2005	1.0	Initial Xilinx release.
12/15/2008	1.1	Added “a” min. 2.00 and max. 2.20 on the dimension table and updated the notes section.
04/04/2014	1.2	Added Figure 2, pin gate mold package as described in XCN12023 .

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